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Transmission by the I²C Bus Interface 3 Module in Single-Master Operation (EEPROM Writing)

Introduction

This application note describes transmission by the I^2C bus interface 3 module (IIC3) of the SH7263/SH7203 in the case of a single master on the I^2C bus.

Target Device

SH7263/SH7203

Contents

1.	Preface	2
2.	Description of the Sample Application	3
	Listing of the Sample Program	
4.	Documents for Reference	18



1. Preface

1.1 Specifications

- In a single-master configuration with the SH7263/SH7203 as the master device and the EEPROM as a slave device, data are written to an EEPROM.
- The transfer rate is set at 397 kHz.

Note: Please adjust settings as required to match the specification of the EEPROM you are using.

1.2 Module Used

• I²C bus interface 3 (IIC3) channel 3

1.3 Applicable Conditions

٠	MCU:	SH7263/SH7203	
٠	Operating frequency:	Internal clock	200 MHz
		Bus clock	66.67 MHz
		Peripheral clock	33.33 MHz
٠	C compiler:	SuperH RISC eng	ine Family C/C++ Compiler Package Ver.9.01 Release01
		from Renesas Tec	hnology
٠	Compiler options:	-cpu = sh2a -inclu	de = "\$(WORKSPDIR)\inc"
		-object = "\$(CON	FIGDIR)\\$(FILELEAF).obj" -debug -gbr = auto -chgincpath
		-errorpath -global	_volatile = 0 -opt_range = all -infinite_loop = 0 -del_vacant_loop = 0
		$-struct_alloc = 1 - 1$	nologo
٠	EEPROM:	HN58X24128FPI	E (128 Kbits)
		from Renesas Tec	hnology

1.4 Related Application Note

The operation of the sample program in this application note was confirmed with the configuration specified in the application note "Example of Initial Configuration" for the SH7263/SH7203 (REJ06B0740). Please refer to that document when setting up this sample task.



2. Description of the Sample Application

In this sample program, the SH7263/SH7203 (master device) transfers data to the EEPROM (slave device) by using I^2C bus interface 3 module (IIC3).

2.1 Operational Overview of Module Used

The I²C bus interface 3 (IIC3) module conforms to and provides a subset of the Philips I²C (Inter-IC) bus interface functions. However, the configuration of the registers that control the I²C bus differs in some respects from the register configuration implemented by Philips.

The features of the I²C bus interface 3 (IIC3) for the SH7263/SH7203 are described below.

- I²C bus format and clock-synchronous serial format are selectable.
- Continuous transmission/reception Since the shift register, transmit data register, and receive data register are independent of each other, continuous data transfer is possible.

Table 1 is a list of the features of the available formats, and figure 1 shows a block diagram of the IIC3 module.

Format	Features
I ² C bus format	Start and stop conditions are generated automatically in master mode.
	 Acknowledge output levels are selectable in data reception.
	 Acknowledge bit is automatically loaded in data transmission
	On-chip bit synchronization/wait function
	In master mode, the state of SCL is monitored per bit, and the timing is synchronized automatically. If transmission/reception is not yet possible, set the SCL to low until preparations are completed.
	Six interrupt sources
	1. Transmit data empty (including slave-address match)
	2. Transmit end
	Receive data full (including slave-address match)
	4. Arbitration lost
	5. NACK detection
	6. Stop condition detection
	 Data transfer by the direct memory access controller (DMAC) can be activated by a transmit-data-empty or receive-data-full interrupt request.
	Direct bus drive
	Two pins, SCL and SDA pins, function as NMOS open-drain outputs when the bus drive function is selected.
Clock-synchronous	Four interrupt sources
serial format	1. Transmit-data-empty
	2. Transmit-end
	3. Receive-data-full
	4. Overrun error
	 Data transfer by the direct memory access controller (DMAC) can be activated by a transmit-data-empty or receive-data-full interrupt request.

Table 1Features of the Formats

Note: For details on IIC3, see the section on I²C Bus Interface 3 (IIC3) of the SH7263/SH7203 Group Hardware Manual (REJ09B0290/REJ09B0313).



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation

(EEPROM Writing)

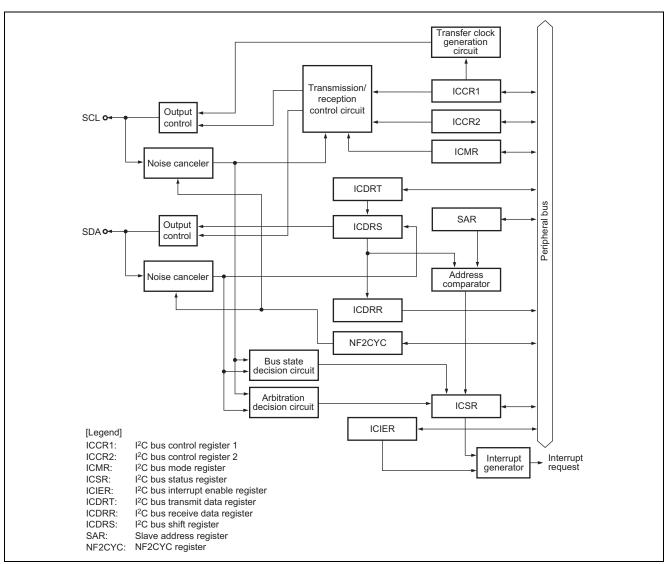


Figure 1 Overview of I²C Bus Interface 3



2.2 Procedure for Setting Module Used

This section describes the procedure for making initial settings for IIC3. The transfer rate must be set to meet the external specification. In this sample program, $P\phi/84$ is specified as the transfer rate. Figure 2 shows an example of the initialization sequence for IIC3. For details on the settings of individual registers, see the *SH7263/SH7203 Group Hardware Manual (REJ09B0290/REJ09B0313)*.

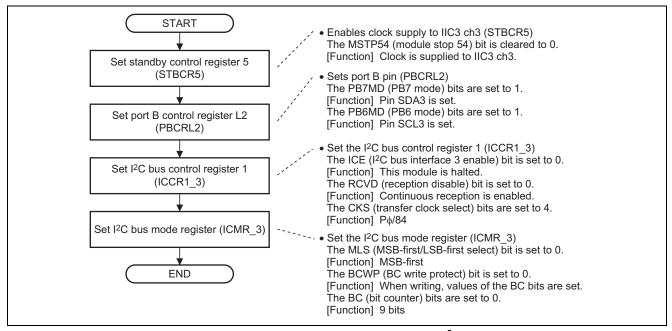


Figure 2 Example of the Initialization Sequence for I²C Bus Interface 3



2.3 Operation of the Sample Program

In this sample program, IIC3 is placed in master transmit mode, and transmits 10 bytes for writing to a page within the EEPROM.

The device code employed in this sample program is "B'1010". Consult the datasheet of the EEPROM you are using for its device code.

The device address employed in this sample program is "B'000". Consult the datasheet of the EEPROM you are using for its device address.

The memory address indicates the point where writing to the EEPROM starts. Each time a byte is written to the EEPROM, the address is incremented.

Figure 3 shows the operations for writing to a single page, and figure 4 shows the operating environment of this sample program.

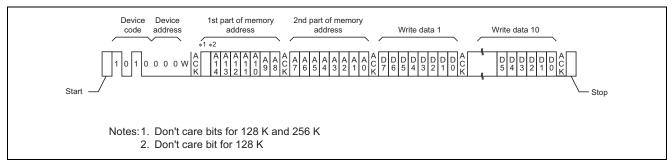


Figure 3 Page Write Operation

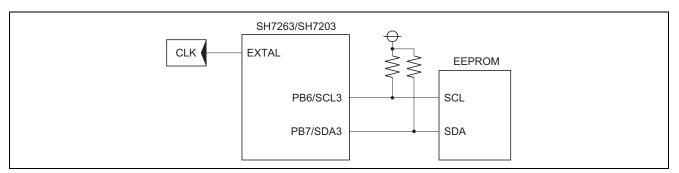


Figure 4 Operating Environment of the Sample Program



2.4 Sequence of Processing by the Sample Program

Table 2 gives the register settings in the sample program. Table 3 shows macro definitions in the sample program. Figures 5 to 8 show the flow of processing by the sample program.

Table 2 Register Settings Used in Sample Program

Register Name	Address	Setting Value	Description
Standby control register 5 (STBCR5)	H'FFFE 0410	H'00	MSTP54 = "0": IIC3-3 operates.
I ² C bus control register 1 (ICCR1_3)	H'FFFE EC00	H'B4	ICE = "1": SCL and SDA pins are placed in bus-drive state. RCVD = "0": Continuous reception is enabled. MST = "1", TRS = "1": Master transmit mode CKS = "B'0100": transfer rate Pφ/84
I ² C bus mode register (ICMR_3)	H'FFFE EC02	H'30	MLS = "0": MSB-first BCWP = "0": Allows the writing of values to the BC bits. BC = "B'000":9 bits

Table 3 Macro Definitions Used in Sample Program

Macro Definition	Setting Value	Description
EEPROM_MEM_ADDR	H'0000	EEPROM start address
DEVICE_CODE	H'A0	Device code
DEVICE_ADDR	H'00	Device address
IIC_DATA_WR	H'00	Write code
IIC_DATA_RD	H'01	Read code
IIC3_DATA	10	Data transfer size

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Transmission by the I²C Bus Interface 3 Module in Single-Master Operation (EEPROM Writing)

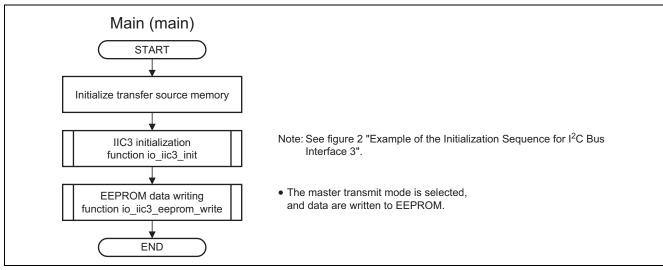


Figure 5 Flow of Processing by the Sample Program (1)



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation (EEPROM Writing)

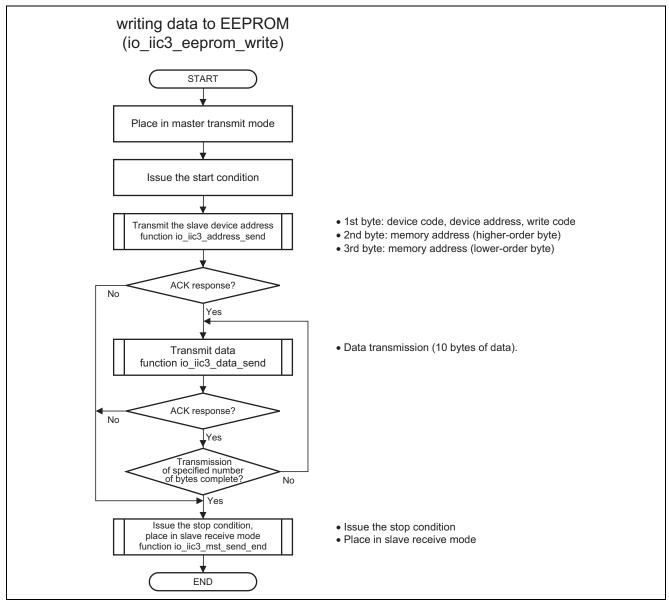


Figure 6 Flow of Processing by the Sample Program (2)





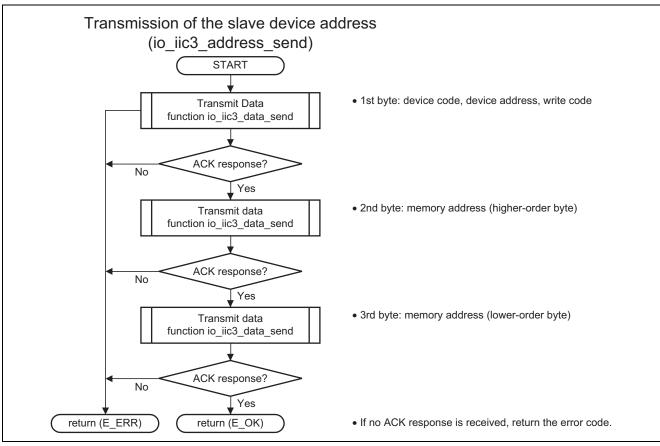


Figure 7 Flow of Processing by the Sample Program (3)



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation (EEPROM Writing)

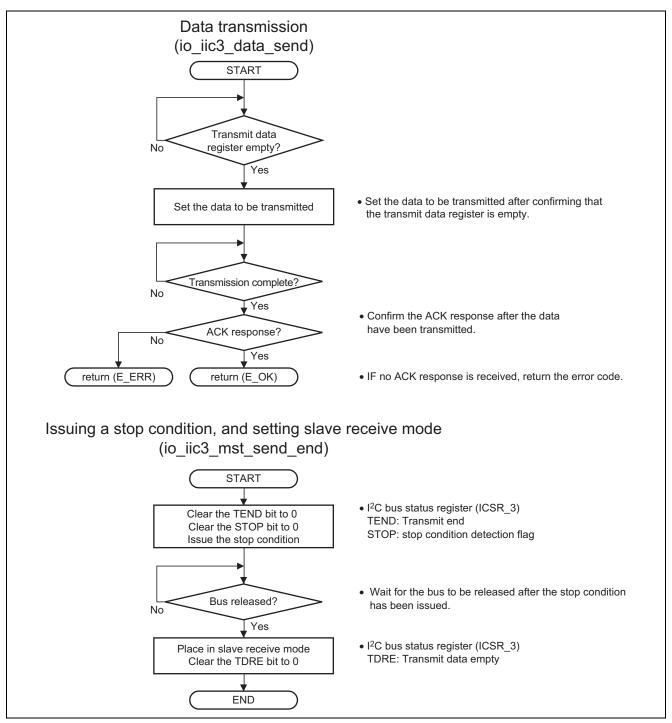


Figure 8 Flow of Processing by the Sample Program (4)



3. Listing of the Sample Program

1. Sample Program Listing: main.c (1)

```
1
 2
    * System Name : SH7263 Sample Program
 3
    * File Name
 4
                  : main.c
 5
     * Contents
                  : Sample program for transmission by IIC3 in master transmit mode
     * Version
 6
                  : 1.00.00
 7
     * Model
                  : R0K572630D001BR
     * CPU
 8
                  : SH7263
     * Compiler : SHC9.1.1.0
 9
     * note
                 : Data are transmitted to EEPROM
10
11
                   by using IIC3 in master transmit mode.
12
     * The information described here may contain technical inaccuracies or
13
   * typographical errors. Renesas Technology Corporation and Renesas Solutions
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17
18
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19
20
21
     * history : 2008.06.05 ver.1.00.00
     22
23
    #include <machine.h>
   #include "iodefine.h"
                              /* SH7263 iodefine */
24
25
     /* ==== symbol definition ==== */
26
27
     #define EEPROM_MEM_ADDR 0x0000
     #define DEVICE_CODE 0xA0 /* EEPROM device code :b'1010
28
                                                              */
                              /* EEPROM device address:b'000
29
     #define DEVICE_ADDR 0x00
                                                              */
                              /* Data write code :b'0
    #define IIC_DATA_WR 0x00
                                                              */
30
    #define IIC_DATA_RD 0x01
                              /* Data read code :b'1
                                                              */
31
    #define IIC3_DATA 10
32
33
34
   #define E_OK 0
35
   #define E_ERR -1
36
37
    /* ==== RAM allocation variable declaration ==== */
38
    unsigned char WriteData[IIC3_DATA];
39
40
     /* ==== prototype declaration ==== */
41
     void main(void);
42
     int io_iic3_eeprom_write(unsigned char d_code, unsigned char d_adr,
                            unsigned short w_adr, unsigned int w_size, unsigned char* w_buf);
43
44
     int io_iic3_data_send(unsigned char data);
45
   int io_iic3_address_send(unsigned char* data);
46
   void io_iic3_mst_send_end(void);
47
   int io_iic3_init(void);
48
```



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation

(EEPROM Writing)

```
2. Sample Program Listing: main.c (2)
```

```
49
50
   * Outline
            : Sample program main
51
   *_____
   * Include
52
            :
   *_____
53
   * Declaration : void main(void);
54
   *_____
55
          : Sample program main
56
   * Function
57
   *_____
58
   * Argument
            : void
   *_____
59
60
   * Return Value : void
   *_____
61
   * Notice
62
           :
   63
   void main(void)
64
65
  {
66
     int i;
      /* ==== Prepare data to be written ==== */
67
68
     for(i=0;i<IIC3_DATA;i++){</pre>
69
     WriteData[i] = IIC3_DATA+i;
70
      }
71
     /* ==== IIC3 initialization setting ==== */
     io_iic3_init();
72
     /* ==== Transmission by IIC3 in master transmit mode ==== */
73
74
     io_iic3_eeprom_write( DEVICE_CODE,
                              /* Device code */
                   DEVICE_ADDR,
                                 /* Device address */
75
76
                   0x0000,
                                 /* Start address for data writing */
77
                   sizeof(WriteData), /* Amount of data to be written */
78
                   WriteData);
                                 /* Location for data storage */
79
     while(1){
80
          /* Loop */
81
      }
82
   }
83
```



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation

(EEPROM Writing)

```
3. Sample Program Listing: main.c (3)
      84
 85
      * Outline
               : IIC3 module initialization
     *_____
 86
      * Include
 87
               : #include "iodefine.h"
      *_____
 88
 89
     * Declaration : int io_iic3_init(void);
 90
      *_____
             : IIC3 module initialization
 91
      * Function
      *_____
 92
 93
      * Argument
               : void
      *_____
 94
 95
      * Return Value : E_OK
     *_____
 96
 97
     * Notice
               :
     98
 99
     int io_iic3_init(void)
 100
     {
 101
        CPG.STBCR5.BIT.MSTP54 = 0u;
                              /* Clear the IIC3_3 module standby mode */
 102
 103
        /* ---- PFC setting ---- */
 104
        PORT.PBCRL2.BIT.PB6MD = 1u;
                               /* SCL3 selection */
        PORT.PBCRL2.BIT.PB7MD = 1u;
                              /* SDA3 selection */
 105
 106
        /* ----IIC31 module operation disabled ---- */
 107
        IIC33.ICCR1.BIT.ICE = 0u;
                           /* IIC transfer disabled state */
       IIC33.ICCR1.BIT.ICE = lu;
                            /* IIC3 module operation is enabled */
 108
 109
        IIC33.ICCR1.BIT.RCVD = 0u;
                            /* Continuous reception is to proceed */
        IIC33.ICCR1.BIT.CKS = 4u;
                            /* Transfer rate: P$\04(397 kHz) */
 110
        /* ---IIC bus mode register (ICMR) setting --- */
 111
 112
        IIC33.ICMR.BYTE = 0x30u;
 113
                        /*
 114
                            bit7
                                  : MLS:0 ----- MSB first
115
                            bit6 : WAIT:0 ----- No WAIT insertion
116
                            bit5-4 : Reserve:1 ----- Reserve bit
                                  : BCWP:0----- Unsetting
 117
                            bit3
                            bit2-0 : BC0:0, BC1:0,BC0:0----- IIC format 9-bit
 118
                       */
 119
 120
 121
        return(E_OK);
 122
     }
```

123



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation

(EEPROM Writing)

```
(A)
1
  D
            Listi
                         •
```

4. Samp	Program Listing: main.c (4)
124	*""FUNC COMMENT""***********************************
125	Outline : EEPROM data write
126 127	Include : #include "iodefine.h"
128	
129	Declaration : int io_iic3_mst_send(unsigned char d_code,
130	: unsigned char d_adr,
131	: unsigned short w_adr,
132 133	: unsigned int w_size, : unsigned char* w_buf);
134	
135	Function : The amount of data specified by "w_size"
136	 in the area specified by "w_buf" are written to the EFENCM area if a bu daviage and a bud daviage address and ada".
137 138	: EEPROM specified by device code "d_code" and device address "d_adr". : Memory addresses within the EEPROM are specified by "w_adr".
139	· Memory addresses within the EMFROM are specified by w_adr .
140	Argument : unsigned char d_code : Device code
141	: unsigned char d_adr : Device address
142	: unsigned short w_adr : Address where writing is to start
143 144	: unsigned int w_size : Amount of data to be written : unsigned char* w buf : Location where data are to be written
144	<pre>insigned char d_adr : Device address : unsigned short w_adr : Address where writing is to start : unsigned int w_size : Amount of data to be written : unsigned char* w_buf : Location where data are to be written</pre>
146	Return Value : With ACK response : E_OK : With no ACK response : E_ERR
147	
148 149	Notice :
150	"FUNC COMMENT END""***********************************
151	nt io_iic3_eeprom_write(unsigned char d_code,unsigned char d_adr,unsigned short w_adr,
152	unsigned int w_size,unsigned char* w_buf)
153	
154 155	<pre>int ack = E_OK; int i;</pre>
156	unsigned char send[3];
157	
158	<pre>send[0] = (unsigned char)(d_code ((d_adr & 0x7)<<1) IIC_DATA_WR);</pre>
159 160	<pre>send[1] = (unsigned char)((w_adr>>8) & 0x00ff); send[2] = (unsigned char)(w_adr & 0x00ff);</pre>
161	senu[2] - (unsigned chai)(w_adi & 0x0011);
162	<pre>while(IIC33.ICCR2.BIT.BBSY == lu){</pre>
163	/* Waiting for bus release */
164	}
165 166	<pre>IIC33.ICCR1.BYTE = 0x30u; /* Set to master transmission mode */ IIC33.ICCR2.BYTE = ((IIC33.ICCR2.BYTE & 0xbfu) 0x80u); /* Issue the start condition */</pre>
167	
168	ack = io_iic3_address_send(send); /* Transmit the first, second, and third bytes of data */
169	
170	<pre>if(ack == E_OK){</pre>
171 172	<pre>/* ACK response is received from the specified device */ for(i=0;i<w_size;i++){< pre=""></w_size;i++){<></pre>
173	<pre>ack = io_iic3_data_send(*w_buf++); /* Data transmission */</pre>
174	if(ack == E_ERR){
175	break;
176 177	}
177 178	<pre>} io_iic3_mst_send_end();</pre>
179	}
180	else{
181	/* ACK response is not received from the specified device */
182 183	io_iic3_mst_send_end();
184	} return(ack);
185	
186	



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation

(EEPROM Writing)

5. Sample Program Listing: main.c (5)

* Include	:	
* Declaration	: int io_iic3_address_send	
* Function *		
* Argument	: unsigned char* data : Tr	
* Return Value *	: With ACK response : E : With no ACK response : E	_ок
* Notice *""FUNC COMMEN int io_iic3_add {	:	*********
int ack;	c3 data send(*data++);	/* Slave device address */
if(ack == H		
} ack = io_ii if(ack == H		<pre>/* 1st part of memory address */</pre>
} ack = io ii	<pre>return(ack); c3 data send(*data);</pre>	<pre>/* 2nd part of memory address */</pre>
if(ack == H		· · · ·
<pre>} return(ack) }</pre>	;	
/*""FUNC COMME	NT""***********************************	**************************************
*		
*		
	: int io_iic3_data_send(un	signed char data);
* Function * *	: Data are transmitted acc : 1. Wait for ICDRT to bec : 2. Set the data to be tr : 3. Check completion of d	ansmitted.
*	: 4. Check the ACK respons	e.
	: unsigned char data : Tra	nsmit data
	: With ACK response : E	
* Return Value *	: With no ACK response : E_	



Transmission by the I²C Bus Interface 3 Module in Single-Master Operation

(EEPROM Writing)

```
6. Sample Program Listing: main.c (6)
```

```
242
    int io_iic3_data_send(unsigned char data)
243
    {
244
       int ack;
245
246
       while(IIC33.ICSR.BIT.TDRE == 0u) {
247
              /* Wait for ICDRT to become empty */
248
       }
249
       IIC33.ICDRT = data;
250
       while(IIC33.ICSR.BIT.TEND == 0u){
251
              /* Wait for completion of data transmission */
252
       }
253
       if(IIC33.ICIER.BIT.ACKBR == 0u){
254
       ack = E_OK;
255
      }
256
       else{
257
             ack = E_ERR;
258
       }
259
       return(ack);
260
   }
    261
262
    * Outline
             : Issuing of a stop condition
263
    *_____
264
    * Include
             : #include "iodefine.h"
265
    *_____
266
    * Declaration : void io_iic3_mst_send_end(void);
    *_____
267
268
    * Function
              : A stop condition is issued and slave receive mode is set.
    *_____
269
270
    * Argument
              : void
    *_____
271
272
    * Return Value : void
273
    *_____
274
     * Notice
              :
    275
276
    void io_iic3_mst_send_end(void)
277
    {
278
      IIC33.ICSR.BIT.TEND = 0u;
                             /* Clear the TEND flag */
279
       IIC33.ICSR.BIT.STOP = 0u;
                              /* Clear the STOP flag */
      IIC33.ICCR2.BYTE &= 0x3fu;
                             /* Issue the stop condition */
280
281
282
       while(IIC33.ICSR.BIT.STOP == 0u){
283
              /* Wait for bus release */
284
      }
285
286
       IIC33.ICCR1.BYTE &= 0xcfu; /* Slave receive mode */
       IIC33.ICSR.BIT.TDRE = 0u;
287
                             /* Clear bit TDRE */
288
    }
289
    /* End of File */
```



4. Documents for Reference

 Software Manual SH-2A, SH2A-FPU Software Manual (REJ09B0051) The most up-to-date version of this document is available on the Renesas Technology Website.

• Hardware Manual

SH7203 Group Hardware Manual (REJ09B0313)The most up-to-date version of this document is available on the Renesas Technology Website.SH7263 Group Hardware Manual (REJ09B0290)The most up-to-date version of this document is available on the Renesas Technology Website.



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